

© EPODOC / EPO

PN - JP2002164257 A 20020607  
PD - 2002-06-07  
PR - JP20000356995 20001124  
OPD - 2000-11-24  
TI - LAMINATED CERAMIC ELECTRONIC COMPONENT  
IN - AIBA TAKASHI;KUME HISASHI;OKABE MASAYUKI;YOSHII  
AKITOSHI  
PA - TDK CORP  
IC - H01G4/30 ; H01G4/12

© WPI / DERWENT

TI - Laminated ceramic electronic component e.g. capacitor has nickel plated layer of specific thickness formed by electrodeposition plating in external terminal electrode  
PR - JP20000356995 20001124  
PN - JP2002164257 A 20020607 DW200256 H01G4/30 004pp  
PA - (DENK ) TDK CORP  
IC - H01G4/12 ;H01G4/30  
AB - JP2002164257 NOVELTY - The thickness of nickel plated layer (5b) of the external terminal electrode (5), formed by electrodeposition plating is set to 0.1-1.0  $\mu$ m.  
- USE - Laminated ceramic electronic components such as ceramic capacitor, varistor, dielectric resonator and piezoelectric element for electronic device.  
- ADVANTAGE - Excels in reliability, bending strength and heat resistance property.  
- DESCRIPTION OF DRAWING(S) - The figure shows an expanded sectional view of the laminated ceramic electronic component. (Drawing includes non-English language text).  
- External terminal electrode 5  
- Nickel plated layer 5b  
- (Dwg.1/3)  
OPD - 2000-11-24  
AN - 2002-523740 [56]

© PAJ / JPO

PN - JP2002164257 A 20020607  
PD - 2002-06-07  
AP - JP20000356995 20001124

- IN - KUME HISASHI, IBA TAKASHI, OKABE MASAYUKI, YOSHII AKITOSHI
- PA - TDK CORP
- TI - LAMINATED CERAMIC ELECTRONIC COMPONENT
- AB - PROBLEM TO BE SOLVED: To provide a satisfactorily reliable laminated ceramic electronic component having superior flexure strength and heatcycle resistance.
- SOLUTION: The laminated ceramic electronic component is formed with its external terminal electrode laminated by a first electrode layer 5a of a base electrode layer of Ag-Pd or Cu, a second electrode layer 5b of electrolytic plated layer on the first electrode layer 5a, and a third electrode layer 5c of Sn or Sn-Pb plated layer on both ends of a laminated ceramic element 4, including an internal electrode 3 therein in this order and the electrolytic Ni plated layer, is formed with its thickness in a range of 0.1 to 1.0  $\mu\text{m}$ .
- I - H01G4/30 ; H01G4/12